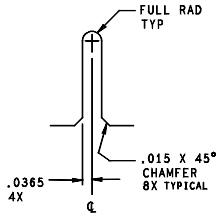
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED

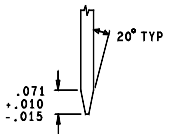
DRILL CHART				
ALL UNITS ARE IN INCHES				
FIGURE	SIZE	PLATED	QTY	
×	0.01	PLATED	453	+.000/-.010
v	0.012	PLATED	382	+.000/-.012
+	0.013	PLATED	9	+.000/-.013
●	0.0135	PLATED	1287	+.000/-.0135
c	0.03	PLATED	32	
L	0.032	PLATED	7	
□	0.042	PLATED	50	
◇	0.043	PLATED	8	
△	0.047	PLATED	62	
○	0.059	PLATED	4	
◆	0.091	PLATED	2	
⊞	0.125	PLATED	6	

NOTES:

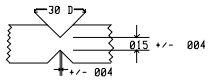
1. PRIMARY / COMPONENT SIDE SHOWN.
2. LAYER ORIENTATION: SEE LAYER DETAIL.
3. MATERIAL: TETRA- OR MULTI- FUNCTIONAL FR-4 LAMINATES AND PREPREGS PER MIL-P-13949. MINIMUM GLASS TRANSITION TEMPERATURE (Tg) OF 170 DEGREE CENTIGRADE REQUIRED. PREPREG & CORE DIELECTRICS MUST BE A MINIMUM 2 PLY.
4. THICKNESS: 0.062" +/- 0.008" (FINISHED)
5. PLATING:
   - 1/2 OZ. PLATED TO 1.5 OZ. ON OUTER LAYERS
   - 1/2 OZ ON INNER SIGNAL LAYERS.
   - 1 OZ. ON PLANE LAYERS (NO PLATE)
   - PLATED THROUGH HOLES SHALL HAVE A MINIMUM AVERAGE COPPER THICKNESS OF .001" WITH AN ABSOLUTE MINIMUM THICKNESS OF .0008", AS MEASURED IN MIL-P-55110.
   - FINGER CONNECTIONS TO BE ELECTROLYTIC HARD GOLD (50-100 MICROINCH) OVER LOW STRESS ELECTROLYTIC NICKEL (200 MICROINCH) PER IPC-D-275, TABLE 3-8 CLASS 2.
6. FINISH: NICKEL GOLD IMMERSION AFTER SOLDER MASK APPLICATION.
7. ANNULAR RING: .002" MINIMUM FOR EXTERNAL ANNULAR RING. .001" MINIMUM FOR INTERNAL ANNULAR RING. TANGENCY IS ACCEPTABLE ON .010" DIA. HOLES.
8. SOLDER MASK: LIQUID PHOTO IMAGEABLE, SOLDER MASK OVER BARE COPPER BOTH SIDES. SOLDER MASK REGISTRATION TO BE WITHIN +/-.003" OF ITS RESPECTIVE CIRCUIT LAYERS, AND NO MASK TO APPEAR ON PADS.
9. BOW AND TWIST: MAXIMUM OF .010 INCH / INCH FOR THROUGH HOLE BOARDS. MAXIMUM OF .0075 INCH / INCH FOR SURFACE MOUNT BOARDS.
10. SILKSCREEN: WHITE NON-CONDUCTIVE INK. NO INK TO APPEAR ON COMPONENT PADS. LINES TO BE .006" MINIMUM.
11. PCB: NOMINAL CONDUCTOR WIDTHS ON FINISHED BOARD TO BE WITHIN +/-15%, OR +/-1 MIL, WHICHEVER IS LESS OF ARTWORK AS DEFINED ON GERBERS AND SUPPLIED APERTURE WIDTH.
12. ELECTRICAL TEST: FINISHED PCB TO BE SUBJECT TO 100% CONTINUITY AND ISOLATION ELECTRICAL TEST. TEST FIXTURES TO BE GENERATED FROM IPC-D-356 FORMATTED NET LIST DATA, CROSS-REFERENCED TO GERBER EXTRACTED NET LIST DATA. VENDOR TO TEST IMPEDANCE ON A COUPON.
13. HOLE CHART: UNLESS OTHERWISE SPECIFIED, ALL TOLERANCES ARE +/- .003"
14. SPACING: MINIMUM FINISHED CONDUCTOR SPACING TO BE 5 MILS
15. SPECIFICATION: UNLESS OTHERWISE SPECIFIED, FAB OF THIS PCB SHALL BE IN CONFORMANCE WITH THE FOLLOWING. IPC-6011 CLASS 2 (GENERIC) IPC-6012 CLASS 2 (RIGID)
16. FLAME CLASS: UL 94V-0 AND MUST MEET REQUIREMENTS OF UL796
17. MOT: MANUFACTURER MUST BE UL RECOGNIZED TO PRODUCE THIS PRODUCT SUCH THAT IT MEET 130 deg C MAXIMUM OPERATING TEMPERATURE
18. MARKINGS: THE FOLLOWING MUST BE MARKED OR ETCHED ON SIDE OF 2 OF PCB IN AREA FREE OF COMPONENT COVERING; DATECODE (YYWW), UL RECOGNIZED VENDOR ID, UL TYPE DESIGNATION, AND/OR MARKING WHICH REFLECT THE SPECIFIED FLAME CLASS AND MAXIMUM OPERATING TEMEPERATURE RATINGS.



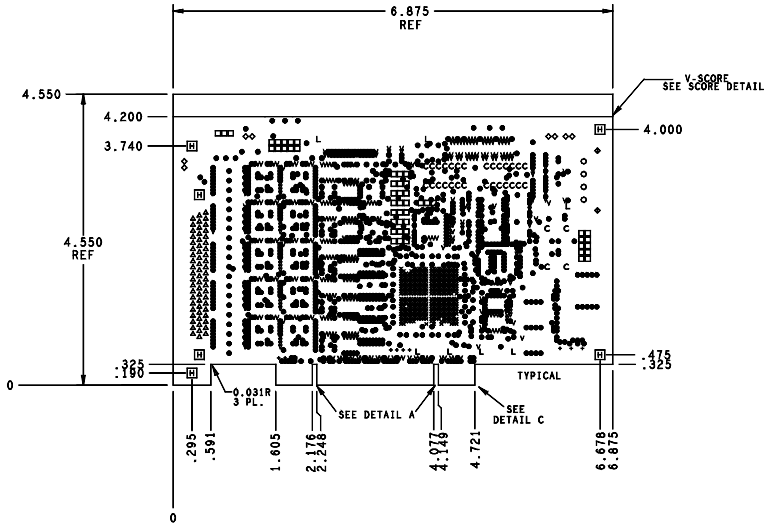
DETAIL A
SCALE: NONE



DETAIL C
SCALE: NONE



SCORE DETAIL
SCALE: NONE



PRIMARY SIDE	LAYER 1		1/2 OZ
INTERNAL SIGNAL 1	LAYER 2		1/2 OZ
GROUND PLANE	LAYER 3		1 OZ
POWER PLANE +2.5/+5	LAYER 4		1 OZ
POWER PLANE +3.3	LAYER 5		1 OZ
GROUND PLANE	LAYER 6		1 OZ
INTERNAL SIGNAL 2	LAYER 7		1/2 OZ
SECONDARY SIDE	LAYER 8		1/2 OZ

LAYER DETAIL
CONSTRUCTION LAMINATE THICKNESS
AT VENDORS' DISCRETION

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TOLERANCES (UNLESS OTHERWISE NOTED)		
.XX +/-.01	FRACTIONAL ANG	
.XXX +/-.005	+/- 1/64	+/-2°
DRAWN	PCBDS	12/03/02
CHECKED		
ENGR APPD		
ENGR APPD		
PROJECT MANAGER		

SIGMET INCORPORATED

TITLE: FABRICATION DRAWING I/O-62

SIZE	DRAWING NUMBER	REV
D	IO-62	B

SCALE 1/1 | SHEET 1 OF 1 PLEXUS @ 80100ED0 | LEVEL